

S/N 10/612,764

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Vassoudevane Lebonheur et al.

Examiner: Victor A. Mandala

Serial No.: 10/612,764

Group Art Unit: 2826

Filed: June 30, 2003

Docket No.: 884.862US1

Title: MOLD COMPOUND CAP IN A FLIP CHIP
MULTI-MATRIX ARRAY PACKAGE AND PROCESS
OF MAKING SAME
Customer Number: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on March 13, 2006. Please amend the above-identified patent application as follows.